

Title (en)  
Wireless chip and manufacturing method of the same

Title (de)  
Drahtloser Chip und Herstellungsverfahren

Title (fr)  
Puce sans fil et méthode de fabrication

Publication  
**EP 1635391 B1 20120118 (EN)**

Application  
**EP 05019377 A 20050906**

Priority  
JP 2004267415 A 20040914

Abstract (en)  
[origin: EP1635391A2] The present invention provides a new type wireless chip that can be used without being fixed on a product. Specifically, a wireless chip can have a new function by a sealing step. One feature of a wireless chip according to the present invention is to have a structure in which an integrated circuit is sealed by one or two films so as to have a space between the integrated circuit and the films. In particular, the films sealing the integrated circuit have a hollow structure; therefore the wireless chip can have a new function. The space can be filled with an inert gas to prevent degradation of the integrated circuit and thus prolong its life, or can be filled with a gas promoting degradation of the integrated circuit to limit its life, making the chip useful in the fields of security or privacy. The sealing step is performed by applying heat using, for example, laser or a heated wire.

IPC 8 full level  
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**EP 1635391 A2 20060315; EP 1635391 A3 20070509; EP 1635391 B1 20120118**; CN 100530611 C 20090819; CN 1767179 A 20060503;  
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